



60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	Q _G Typ	I _D Max T _C = +25°C (Note 10)
60V	$3.8m\Omega$ @ $V_{GS} = 10V$	95.4nC	100A

Features

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R_{DS(ON)} Minimizes Power Losses
- Low Q_G Minimizes Switching Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters
- Motor Control

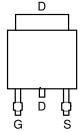
Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.33 grams (Approximate)

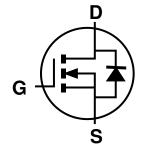




Top View



Top View Pin Out



Internal Schematic

Ordering Information (Note 5)

Part Number	Case	Packaging
DMTH6004SK3Q-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



T6004S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	60	V		
Gate-Source Voltage	V_{GSS}	±20	V		
Continuous Drain Current (Note 7)	T _C = +25°C (Note 10)	I _D	100	А	
	$T_{C} = +100^{\circ}C$		75		
Maximum Body Diode Forward Current (Note 7)	Is	100	Α		
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)	I _{DM}	150	Α		
Avalanche Current, L = 0.2mH	I _{AS}	45	Α		
Avalanche Energy, L = 0.2mH	Eas	200	mJ		

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	$T_A = +25$ °C	P_{D}	3.9	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	38	°C/W	
Total Power Dissipation (Note 7) $T_C = +25^{\circ}C$		P_{D}	180	W
Thermal Resistance, Junction to Case (Note 7)	R _{eJC}	0.8	°C/W	
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

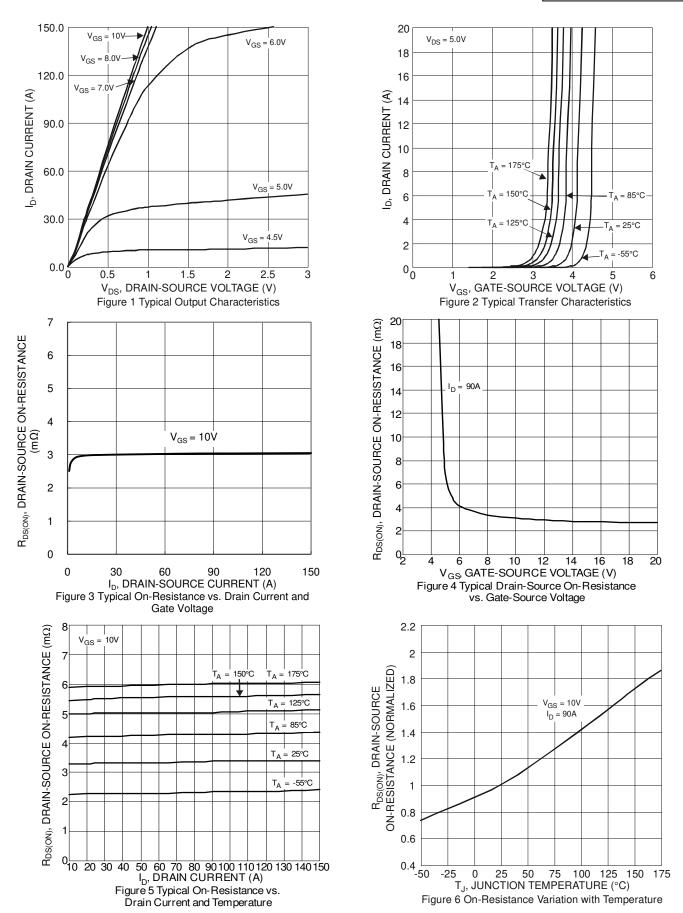
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	V _{DS} = 48V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	2		4	V	$V_{DS} = V_{GS}, \ I_D = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	3	3.8	mΩ	$V_{GS} = 10V, I_D = 90A$	
Diode Forward Voltage	V_{SD}	_	0.9	1.2	V	$V_{GS} = 0V, I_S = 20A$	
DYNAMIC CHARACTERISTICS (Note 9)	DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{ISS}	_	4,556		pF	$V_{DS} = 30V, V_{GS} = 0V, f = 1MHz$	
Output Capacitance	Coss	_	1,383	_			
Reverse Transfer Capacitance	C _{RSS}	_	105.2	_			
Gate Resistance	R _G		0.66		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q _G	_	95.4	_			
Gate-Source Charge	Q _{GS}	_	21.6	_	nC	$V_{DS} = 30V$, $I_D = 90A$, $V_{GS} = 10V$	
Gate-Drain Charge	Q_{GD}	_	20.4	_			
Turn-On Delay Time	t _{D(ON)}	_	13.2	_		$\begin{split} V_{DD} &= 30 V, V_{GS} = 10 V, \\ I_D &= 90 A, R_G = 3.5 \Omega \end{split}$	
Turn-On Rise Time	t _R	_	11.7	_			
Turn-Off Delay Time	t _{D(OFF)}	_	31	_	ns		
Turn-Off Fall Time	t _F	_	12	_			
Body Diode Reverse Recovery Time	t _{RR}	_	50.5	_	ns nC I _F = 50A, di/dt = 100A/µs		
Body Diode Reverse Recovery Charge	Q _{RR}	_	80.8	_			

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.7. Thermal resistance from junction to soldering point (on the exposed drain pad).8. Short duration pulse test used to minimize self-heating effect. Notes:

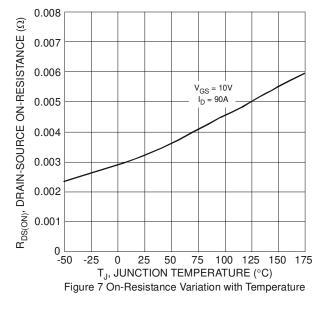
^{9.} Guaranteed by design. Not subject to production testing.

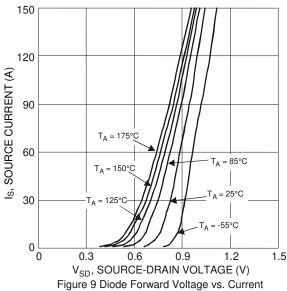
^{10.} Package limited.

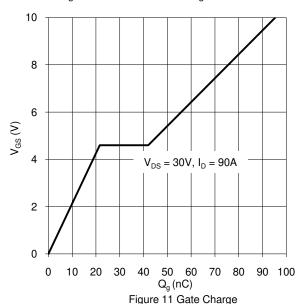


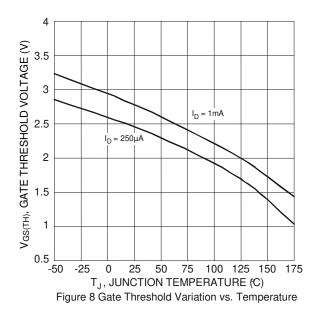


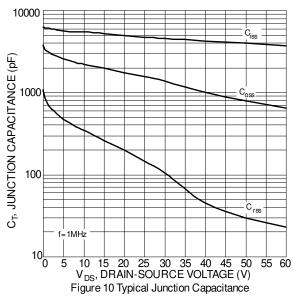












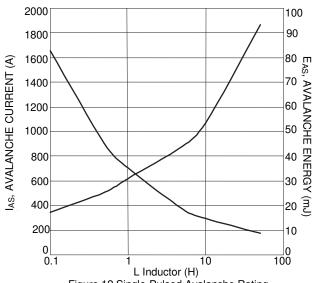
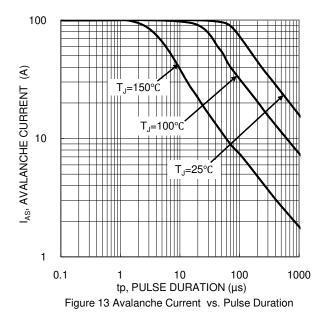
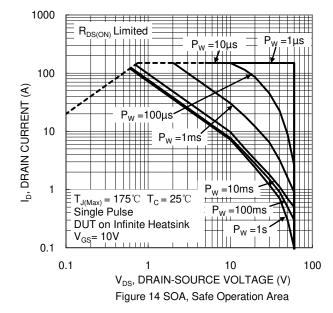
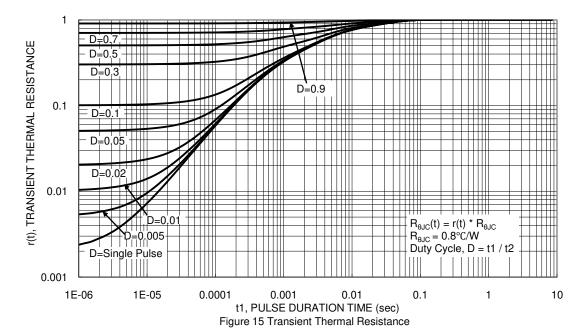


Figure 12 Single-Pulsed Avalanche Rating







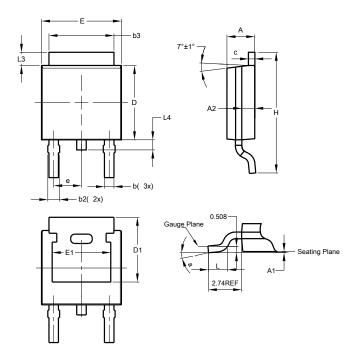




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

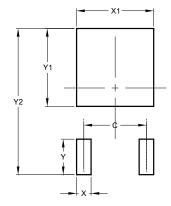


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	_	_		
е	_	_	2.286		
Е	6.45	6.70	6.58		
E1	4.32	_	_		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	_		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)			
С	4.572			
Х	1.060			
X1	5.632			
Υ	2.600			
Y1	5.700			
Y2	10.700			



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